IN THE CLAIMS:

Amend the claims as follows:

1. (Previously Presented) A process for the manufacturing of a decorative laminate, which laminate comprises an uppermost and lower visible surface, the uppermost surface comprising a decorative and abrasion resistant thermosetting laminate layer; a carrying core, beneath the uppermost surface wherein the core comprises fiber board and wherein an upper side of the core is provided with the abrasion resistant thermosetting laminate and that the lower visible surface consists of a balance layer, said balance layer having the purpose of preventing warping of said decorative laminate and at the same time having the purpose of acoustic dampening, said balance layer consisting of a single polymer layer, said polymer consisting of an expanded physically cross-linked polyolefin with closed cells whereby said balance layer and said thermosetting laminate are joined with said fiber board core by pressing, whereupon the achieved laminate is cut into panels and provided with edges intended for joining.

2. (Previously Presented) A process according to claim 1, wherein the thermosetting laminate is constituted by one or more decor papers impregnated with melamine-formaldehyde resin and one or more overlay sheets impregnated with melamine formaldehyde resin arranged on top of the decor papers and possibly one or more resin impregnated underlay papers, arranged under the decor paper or decor papers, which papers are laminated together under increased pressure and increased temperature.

3. (Cancelled).

4. (Cancelled).

5-9. (Cancelled).

10. (Currently Amended) A process according to claim 2, wherein at least one of the sheets impregnated with thermosetting resin is provided with hard particles with an average size of ~~1—100 Φ m~~ 1-100 μm.

11. (Previously Presented) A process according to claim 2, wherein the thermosetting laminate has a thickness in the range 0.3 mm - 1.2 mm.

12. (Previously Presented) A process according to claim 2, wherein the thermosetting laminate has a density in the range 1250 - 1500 kg/m^3.

13. (Cancelled).

14. (Previously Presented) A process according to claim 1, wherein the balance layer has an elasticity compression coefficient in the range 0.5 - 2.7 MPa.

15. (Previously Presented) A process according to claim 1, wherein the balance layer has a thickness in the range 0.1 - 5 mm.

16. (Previously Presented) A process according to claim 1, wherein the balance layer has a density in the range 50 - 400 kg/m^3.

17. (Previously Presented) A process according to claim 1, wherein the balance layer is joined with the carrying core by means of glue and pressure.

18--23. (Cancelled).

24. (Previously Presented) A process according to claim 1, wherein the balance layer further comprises a conductive material.

25. (Previously Presented): A process according to claim 24, wherein the conductive material comprises carbon black.

26. (Previously Presented): A process according to claim 24, wherein the conductive material comprises carbon fibre.

27. (Previously Presented): A process according to claim 24, wherein the conductive material comprises a vacuum metallized layer.

28. (Previously Presented): A process according to claim 24, wherein the conductive material comprises aluminum.

29. (Previously Presented) A process according to claim 24, wherein a conductivity is better than 500 kΩcm.

30. (Previously Presented) A process according to claim 1, wherein the thermosetting laminate is joined with the carrying core by means of glue and pressure.

31. (Previously Presented) A process according to claim 1, wherein at least one of the balance layer and the thermosetting laminate is joined with the carrying core by at least one of of melt-glue, heat and pressure.

32. (Previously Presented) A process according to claim 63, wherein at least one of the balance layer and the thermosetting laminate is joined with the carrying core by at least one of glue, heat and pressure.

33. (Previously Presented) A process according to claim 32, wherein the glue comprises a conductive material.

34. (Original) A process according to claim 33, wherein the conductive material is constituted of carbon black.

35. (Original) A process according to claim 33, wherein the conductive material is constituted of carbon fibre.

36. (Previously Presented) A process according to claim 33, wherein a conductivity is better than 500 kΩcm.

37. (Previously Presented) A process according to claim 1, wherein the thermosetting laminate has a thickness in the range 0.3 mm - 1.2 mm.

38. (Previously Presented) A process according to claim 37, wherein the thermosetting laminate has a density in the range 1250 - 1500 kg/m^3.

39. (Cancelled).

40. (Previously Presented) A process according to claim 63, wherein the dampening foil has an elasticity compression coefficient in the range 0.5 - 2.7 MPa.

41. (Previously Presented) A process according to claim 63, wherein the dampening foil has a thickness in the range 0.1 - 0.7 mm.

42. (Previously Presented) A process according to claim 63, wherein the dampening foil has a density in the range 150 - 400 kg/m^3.

43. (Previously Presented) A process according to claim 63, wherein the dampening foil and the thermosetting laminate are joined with the carrying core by means of glue and pressure.

44. (Previously Presented) A process according to claim 41, wherein the dampening foil and the thermosetting laminate are joined with the carrying core by means of at least one selected from the group consisting of melt-glue, heat and pressure.

45. (Previously Presented) A process according to claim 41, wherein the dampening foil and the thermosetting laminate are joined with the carrying core by each of melt-glue, heat and pressure.

46. (Previously Presented) A process according to claim 10, wherein the hard particles have an average size of 5 - 60 μm.

47. (Previously Presented) A process according to claim 2, wherein the thermosetting laminate has a thickness in the range 0.3 mm - 0.9 mm.

48. (Previously Presented) A process according to claim 1, wherein the balance layer has a thickness in the range 0.2 - 1 mm.

49. (Previously Presented) A process according to claim 1, wherein the balance layer has a density in the range 80 - 330 kg/m^3.

50. (Previously Presented) A process according to claim 1, wherein the thermosetting laminate has a thickness in the range 0.3 mm - 0.9 mm.

51. (Previously Presented) A process according to claim 63, wherein the dampening foil has an elasticity compression coefficient in the range 0.8 - 2.0 MPa.

52. (Previously Presented) A process according to claim 63, wherein the dampening foil has a thickness in the range 0.1 - 0.5 mm.

53. (Previously Presented) A process according to claim 63, wherein the dampening foil has a density in the range 180 - 330 kg/m^3.

54. (Previously Presented) A process according to claim 10, wherein the hard particles are at least one selected from the group consisting of silicon oxide, aluminum oxide and silicon carbide.

55. (Previously Presented) A process according to claim 2, wherein the laminate comprises underlay papers and said underlay papers contain phenol-formaldehyde resin.

56-62. (Cancelled).

63. (Previously Presented) The process of claim 1, wherein the carrying core is further provided with a dampening foil of an elastomer arranged between the upper side of the core and the abrasion resistant thermosetting laminate, which elastomer and thermosetting laminate are joined with each other and with the core by pressing.

64. (Previously Presented) The process of claim 1, further comprising adding a bonding layer between the balance layer and the core.

65. (Previously Presented) The process of claim 64, wherein the bonding layer contains a conductive material.